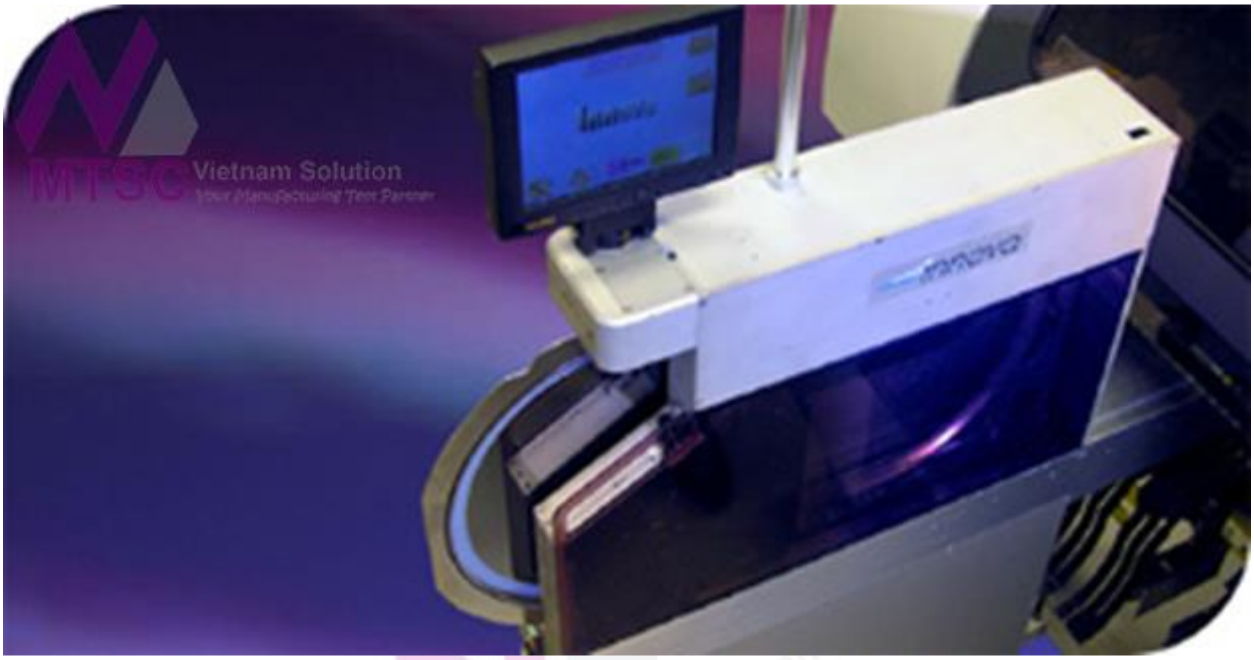

Innova Direct Die Feeders support a full complement of high-volume flip chip and bare die applications. Innova enables high-speed die delivery from wafer over a wide range of die sizes. When integrated with the flexible GenesisSC Platform, Innova eliminates the need for dedicated die presentation systems to streamline processes and improve efficiency.

- ✓ Ideal for SiP applications
- ✓ High-mix to high-volume support
- ✓ Handles up to 300mm wafers
- ✓ Inline barcode scanning supports ALPs or Inkless wafer maps
- ✓ Supports up to 4 per machine

INNOVA MODELS & SPECIFICATIONS

- **Innova** - High-speed flip chip and bare die presentation from a single wafer
- **Innova +** - High-speed flip chip and bare die presentation with a cassette supporting up to 13 wafers

Model	Max Wafers per Feeder	Max Rate (cph) Flip Chip / Bare Die	Min Die Thickness (µm)	Min Die Size (mm)	Wafer Change	Wafer Size (in)	Wafer Expansion
Innova	1	4,700 / 4,000	75	0.7 x 0.7	Manual	4, 6, 8, 12	Offline, grip rings
Innova +	13	4,700 / 4,000	75	0.7 x 0.7	Automatic	4*, 6*, 8*, 12 *Requires 12" frame	Online